

ABSTRACT

A piezoelectric device capable of improving moisture resistance while being miniaturized, which need not be sealed after being mounted on a circuit board, and a manufacturing method of the piezoelectric device are provided. A piezoelectric device 10 includes: a) an element substrate 12 having a piezoelectric element 22 and an electrically conductive pattern 24 connected to the piezoelectric element 22, which are formed on a principal surface 14; b) a supporting layer 30 arranged in the periphery of the piezoelectric element 22 on the principal surface 14 of the element substrate 12; c) a cover 50 extending so as to form a space inside the external periphery of the element substrate 12, the space ranging over the entire external periphery of the element substrate 12, by removing part of elements inside the external periphery of the element substrate 12 viewed from the normal direction of the principal surface 14 of the element substrate 12 after the cover 50 is arranged on the supporting layer 50; d) an insulating reinforcing material 70 that entirely covers portions of the element substrate 12 adjacent to the cover 50 ranging from the cover 50 to the periphery of the principal surface 14 of the element substrate 12; and e) an electrically conductive member electrically connected to the electrically conductive pattern 24 so as to pass through the cover 50 and the reinforcing material 70.